

**N - CHANNEL ENHANCEMENT MODE
POWER MOS TRANSISTOR**

ADVANCE DATA

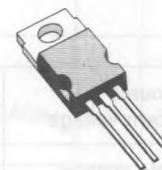
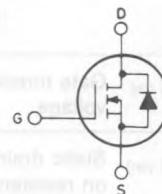
TYPE	V _{DSS}	R _{DS(on)}	I _D
BUZ10	50 V	0.08 Ω	20 A

- HIGH SPEED SWITHING
- LOW R_{DS (ON)}
- EASY DRIVE FOR COST EFFECTIVE APPLICATIONS.

INDUSTRIAL APPLICATIONS:

- AUTOMOTIVE POWER ACTUATOR DRIVES
- MOTOR CONTROLS
- DC-DC CONVERTERS

N - channel enhancement mode POWER MOS field effect transistor. Easy drive and very fast switching times make this POWER MOS transistors ideal for high speed switching circuits in applications such as power actuator driving, motor drives including brushless motors, hydraulic actuators and many other uses in automotive and automatic guided vehicle applications. It is also used in DC/DC converters and uninterruptible power supplies.


TO-220
INTERNAL SCHEMATIC DIAGRAM

ABSOLUTE MAXIMUM RATINGS

V _{DS}	Drain-source voltage (V _{GS} = 0)	50	V
V _{DGR}	Drain-gate voltage (R _{GS} = 20 kΩ)	50	V
V _{GS}	Gate-source voltage	±20	V
I _D	Drain current (continuous) T _c = 30°C	20	A
I _{DM}	Drain current (pulsed)	80	A
P _{tot}	Total dissipation at T _c < 25°C	70	W
T _{stg}	Storage temperature	-55 to 150	°C
T _j	Max. operating junction temperature	150	°C
	DIN humidity category (DIN 40040)	E	
	IEC climatic category (DIN IEC 68-1)	55/150/56	

THERMAL DATA

$R_{thj\text{-case}}$	Thermal resistance junction-case	max	1.78	$^{\circ}\text{C}/\text{W}$
$R_{thj\text{-amb}}$	Thermal resistance junction-ambient	max	75	$^{\circ}\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS ($T_j = 25^{\circ}\text{C}$ unless otherwise specified)

Parameters	Test Conditions	Min.	Typ.	Max.	Unit
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OFF

$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$I_D = 250 \mu\text{A}$	$V_{GS} = 0$	50			V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}$				250	μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{DS} = \text{Max Rating}$	$T_j = 125^{\circ}\text{C}$			1000	μA
		$V_{GS} = \pm 20 \text{ V}$				± 100	nA

ON

$V_{GS\text{(th)}}$	Gate threshold voltage	$V_{DS} = V_{GS}$	$I_D = 1 \text{ mA}$	2.1		4	V
$R_{DS\text{(on)}}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}$	$I_D = 13 \text{ A}$			0.1	Ω

DYNAMIC

g_{fs}	Forward transconductance	$V_{DS} = 25 \text{ V}$	$I_D = 13 \text{ A}$	8			mho
C_{iss}	Input capacitance					700	pF
C_{oss}	Output capacitance					450	pF
C_{rss}	Reverse transfer capacitance	$V_{DS} = 25 \text{ V}$	$f = 1 \text{ MHz}$			180	pF

SWITCHING

$t_d\text{(on)}$	Turn-on time	$V_{DD} = 30 \text{ V}$	$I_D = 3 \text{ A}$	20		ns	
t_r	Rise time	$R_{GS} = 50 \Omega$	$V_{GS} = 10 \text{ V}$	70		ns	
$t_d\text{(off)}$	Turn-off delay time			110		ns	
t_f	Fall time			80		ns	

ELECTRICAL CHARACTERISTICS (Continued)

Parameters	Test Conditions	Min.	Typ.	Max.	Unit
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SOURCE DRAIN DIODE

I_{SD} I_{SDM}	Source-drain current Source-drain current (pulsed)	$T_c = 25^\circ C$		20 20	A A
V_{SD}	Forward on voltage	$I_{SD} = 40 A$	$V_{GS} = 0$		1.5 V
t_{rr} Q_{rr}	Reverse recovery time Reverse recovered charge	$I_{SD} = 20 A$	$di/dt = 100A/\mu s$	150 1.0	ns μC